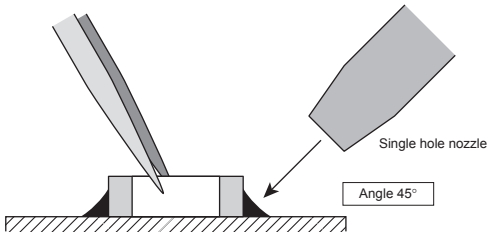
Soldering Method

1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 150 degree Celsius.
2) The product size 1.6×0.8mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of bigger than 3.2×1.6mm, or smaller than 1.6×0.8mm can be used in reflow.
   Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
3) Please see our recommended soldering conditions.
4) In case of using Sn-Zn Solder, please contact us in advance.
5) The following condition is recommended for spot heater application.

• Recommended spot heater condition

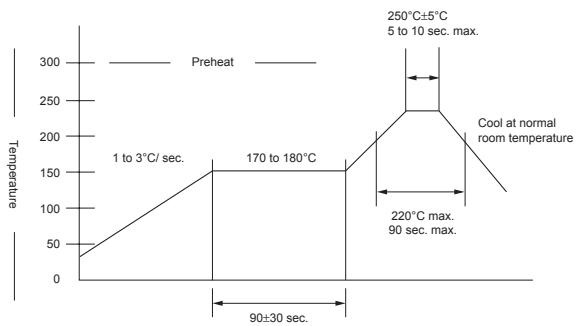
Item	Condition
Distance	5mm min.
Angle	45°
Projection Temp.	400°C max.
Flow rate	Set at the minimum
Nozzle diameter	2ϕ to 4ϕ (Single hole type)
Application time	10 sec. max. (1206 and smaller) 30 sec.max. (1210 and larger)

How to point spot heater



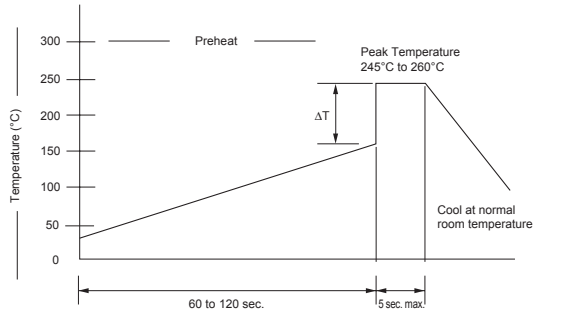
Recommended Temperature Profile (Sn–3Ag–0.5Cu)

Reflow



① Minimize soldering time.
② Ensure that allowable temperature difference does not exceed 150°C.
③ Ensure that allowable temperature difference does not exceed 130°C for 3.2×2.5mm size or larger.

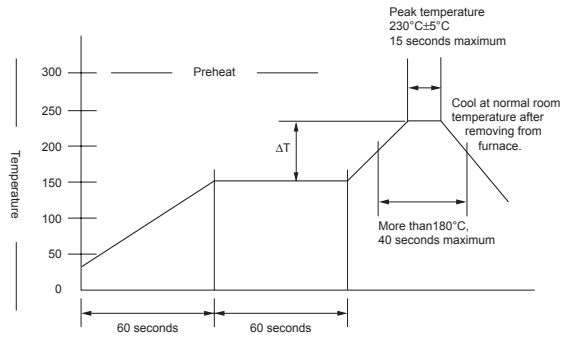
Wave



① Ensure that the chip capacitor is preheated adequately.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Cool naturally after soldering.
④ Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays.

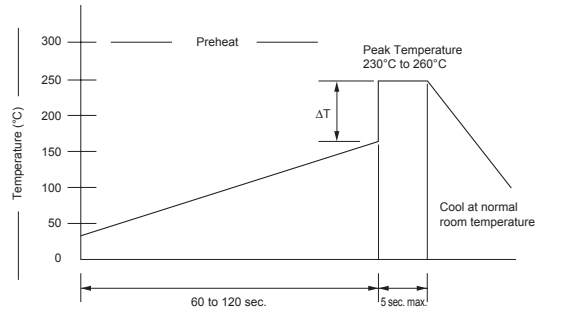
Recommended Temperature Profile (62Sn Solder)

Reflow



① Minimize soldering time.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Ensure that the temperature difference (ΔT) does not exceed 130°C for 3.2×2.5mm size or larger.
④ MLCC can withstand the above reflow conditions up to 3 times.

Wave



① Ensure that the chip capacitor is preheated adequately.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Cool naturally after soldering.
④ Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays.

Soldering iron

1) Temperature of iron chip — 1206 and smaller 350°C max.; 1210 and larger 280°C max.
2) Wattage — 80W max.
3) Tip shape of soldering iron — ϕ3.0mm max.
4) Soldering Time — 3 sec. max.

5) Cautions
   a) Pre–heating is necessary rapid heating must be avoided.
      Delta T≤150°C (product size of bigger than 3.2×1.6mm. Delta T≤130°C)
   b) Avoid direct touching to capacitors.
   c) Avoid rapid cooling after soldering. Natural cooling is recommended.

*Consult as if it is difficult to keep the temperature 280°C max. for 1210 and larger MLCC'S.